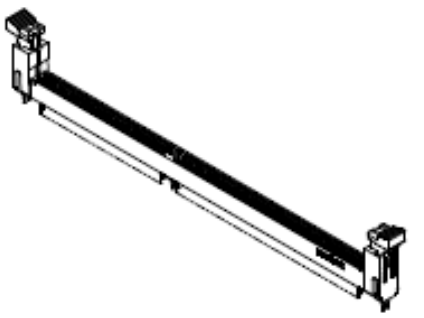
This document was generated on 04/16/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0780790011

Status: Active

Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Vertical, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm (30µ") Gold (Au) Plating, 2.67mm(.105") Soldertail, 240 Circuits, Lead free



Series image - Reference only

Documents:

- 3D Model
- Drawing (PDF)
- Product Specification PS-78079-002 (PDF)
- RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Memory Module Sockets
Series	78079
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Flammability	94V-0
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.105 In
PC Tail Length (mm)	2.67 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.57 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
78079Series

Mates With
JEDEC standard 1.27mm modules

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

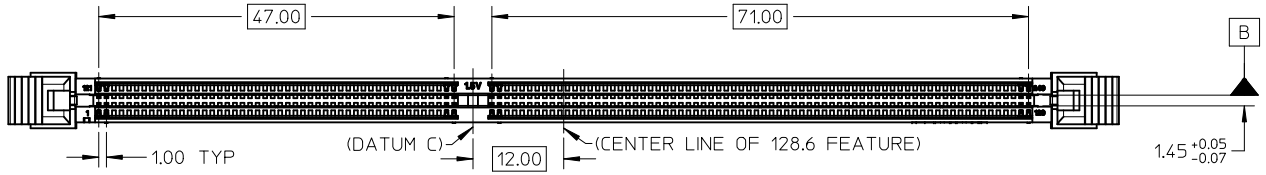
Material Info

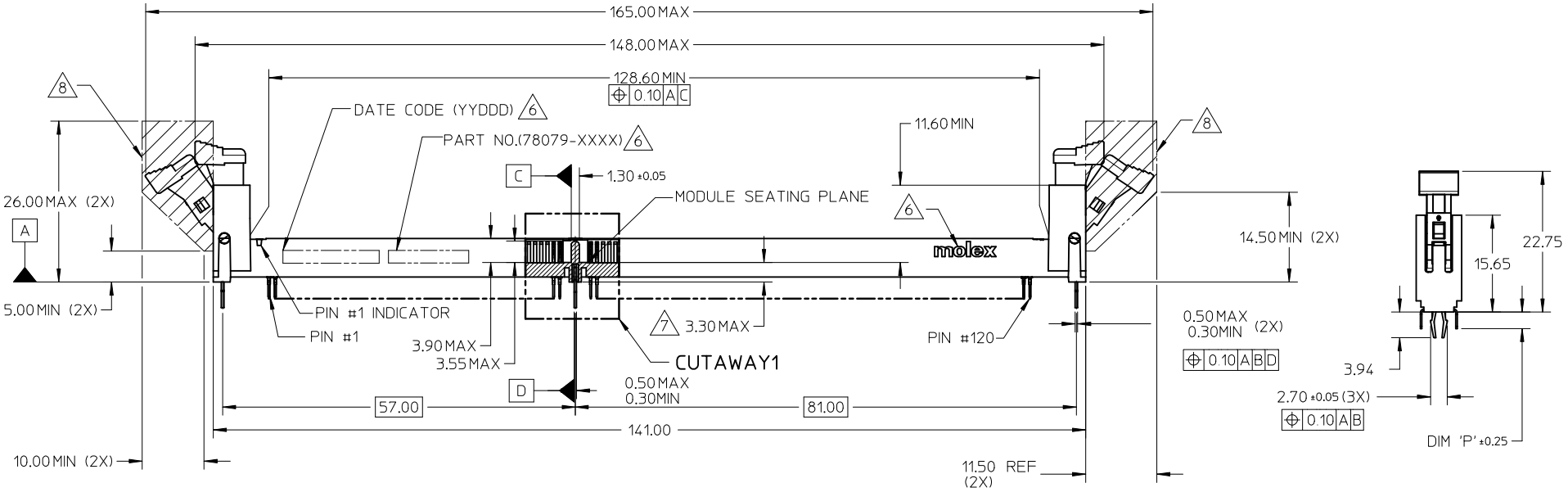
Reference - Drawing Numbers

Product Specification	PS-78079-002
Sales Drawing	SD-78079-001

This document was generated on 04/16/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION





NOTES :

1. MATERIAL : HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0
   COLOUR : SEE SHEET 6 AND 7
   LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
   COLOUR : SEE SHEET 6 AND 7
   TERMINAL : COPPER ALLOY.
2. TERMINAL PLATING OPTIONS: SEE TABLE ON SHEETS 6 & 7.
3. PRODUCT SPECIFICATION: SEE TABLE ON SHEETS 6 & 7.
4. PACKAGING INFORMATION: PRODUCT SHALL BE PACKED IN TRAY
5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).

6. MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
7. MODULE SEATING PLANE FROM TOP OF PCB.
8. KEEP OUT ZONE RESERVED FOR LATCH.

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
FA=0
FC=0
FB=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

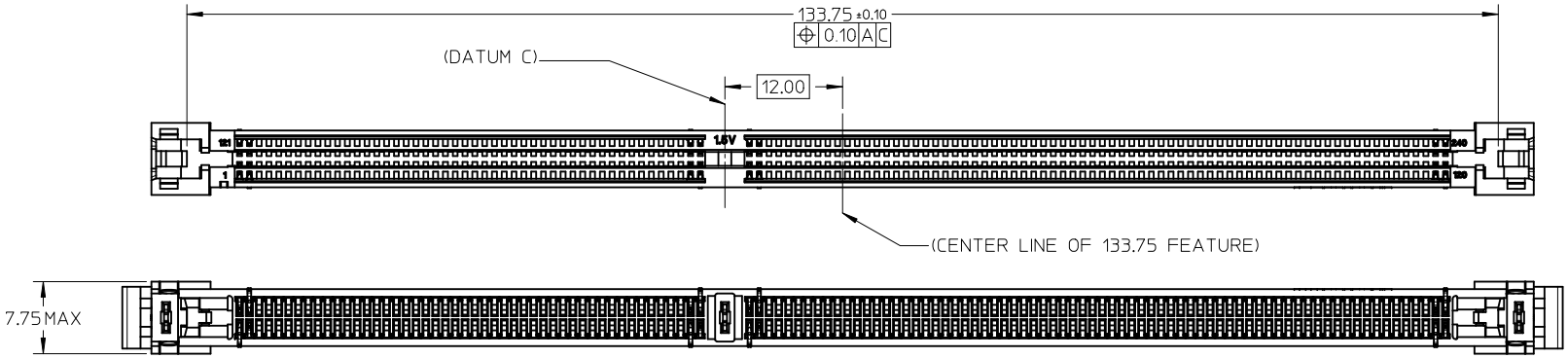
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

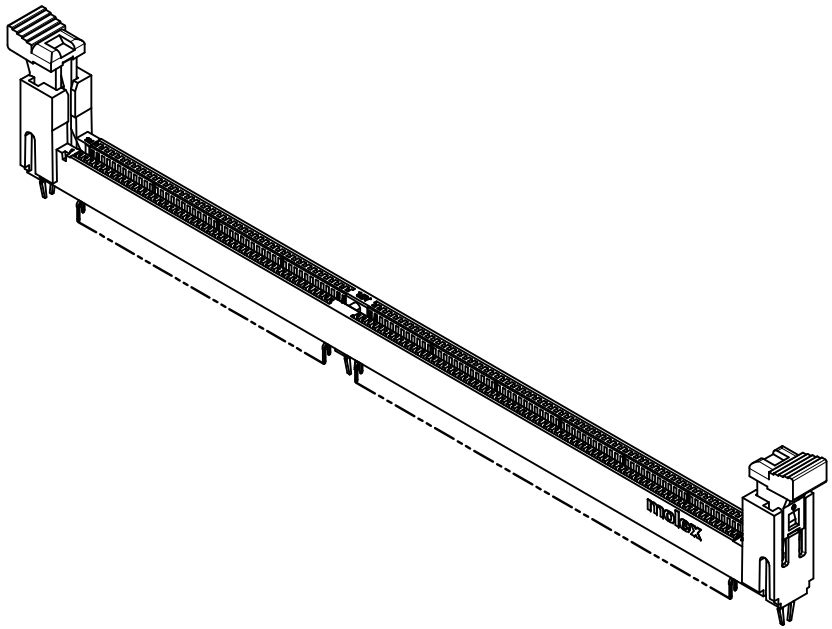
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: NTS	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: YTYANG01 DATE: 2006/08/11	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H		
CHECKED BY: SHLENI DATE: 2006/09/07			
APPROVED BY: SHLENI DATE: 2010/06/10	MOLEX INCORPORATED		
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-78079-001	SHEET NO.: 1 OF 8	

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





FORKLOCK UPDATED	EC NO: S2010-0888	2010/04/29			
	DRWN: JAKEEMEW	2010/06/10			
	CH'KD: CCTEH	2010/06/13			
	APPR: SHLENI				
A4	DESCRIPTION	REV			

QUALITY SYMBOLS

$\sqrt{F_A}=0$

$\sqrt{F_C}=0$

$\sqrt{F_P}=0$

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY		
SCALE	NTS	DESIGN UNITS	METRIC
			THIRD ANGLE PROJECTION
DRAWN BY	YTYANG01	DATE	2006/08/11
CHECKED BY	SHLENI	DATE	2006/09/07
APPROVED BY	SHLENI	DATE	2010/06/10
MATERIAL NO.	SEE TABLE		
SIZE	A3		

TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H

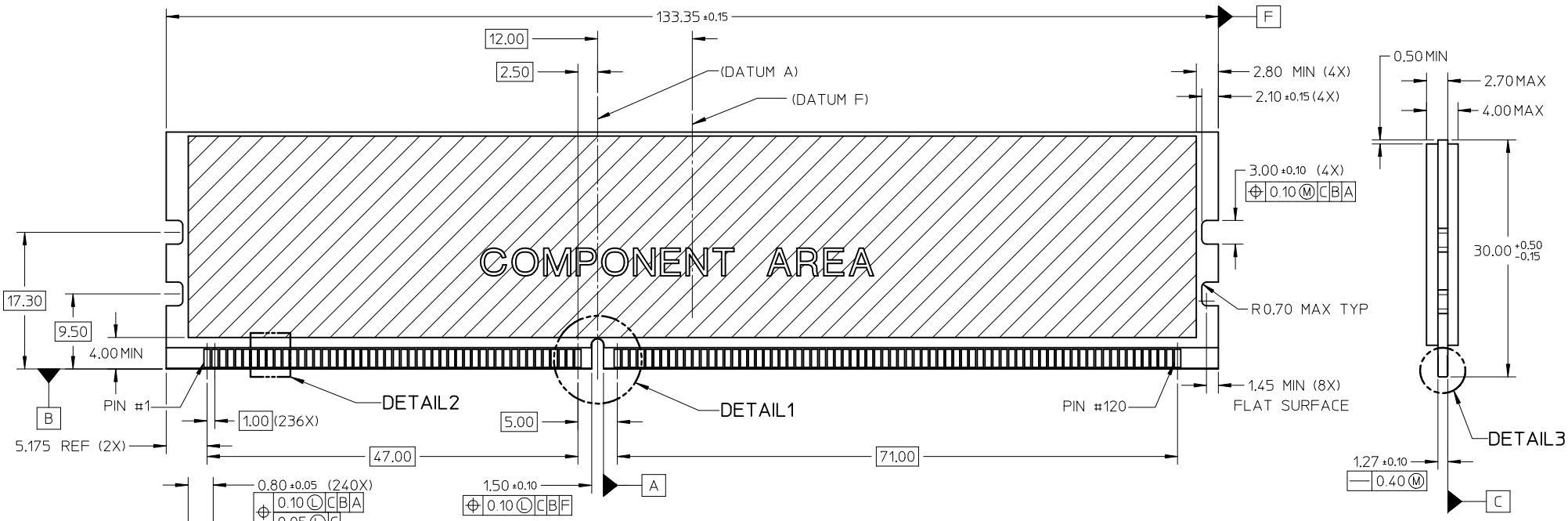
MOLEX INCORPORATED

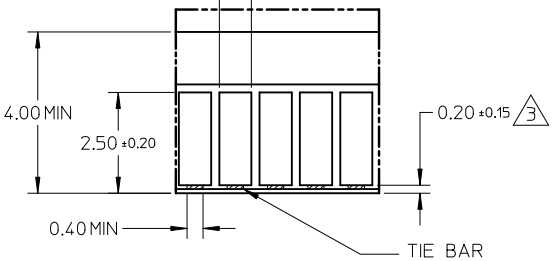
DOCUMENT NO. SD-78079-001

SHEET NO. 2 OF 8

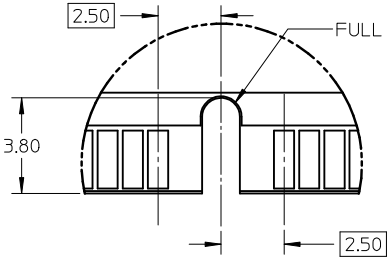
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODULE CARD
DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
(JEDEC MO-269, ISSUE B, MAY 06)

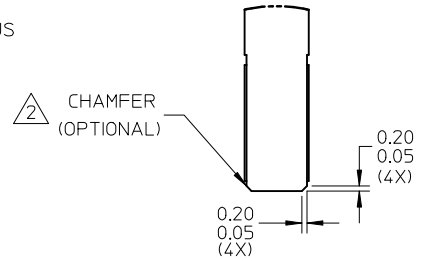




DETAIL2



DETAIL1



DETAIL3

NOTES:
1. RECOMMENDED PLATING FOR CONTACT PADS:
   PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
   OVER 2.00 MICROMETERS NICKEL
   ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
   OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC
   CONTACT GRADE CORROSIVE BARRIER LUBRICANT
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
   SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
FA=0
FC=0
FB=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10

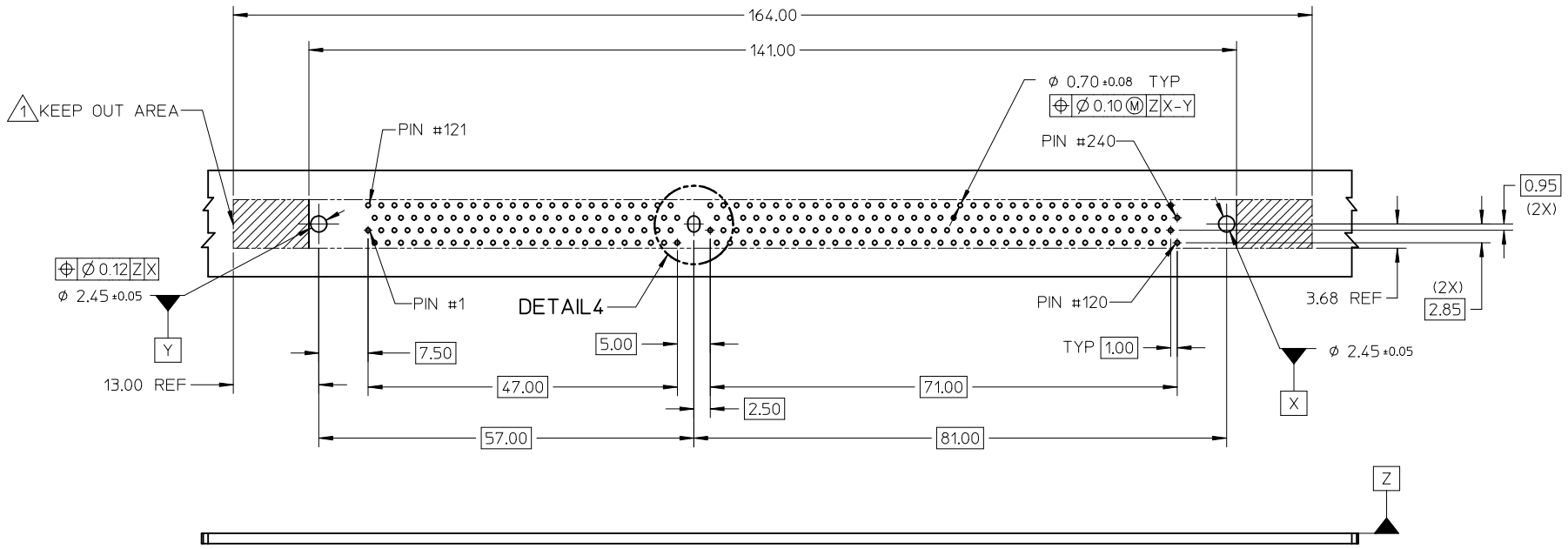
TITLE: DDR3 DIMM, 1.00MM PITCH
240 CKTS, VERTICAL T/H

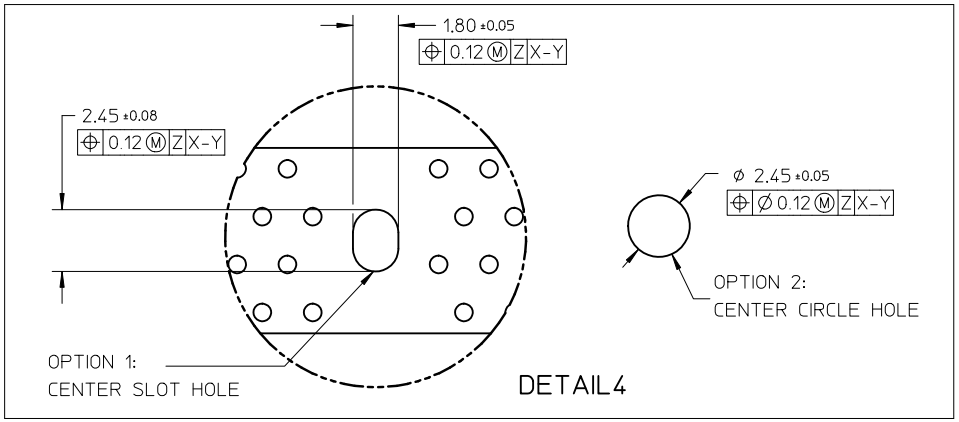
MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78079-001
SHEET NO.: 3 OF 8

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





NOTE:
1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10

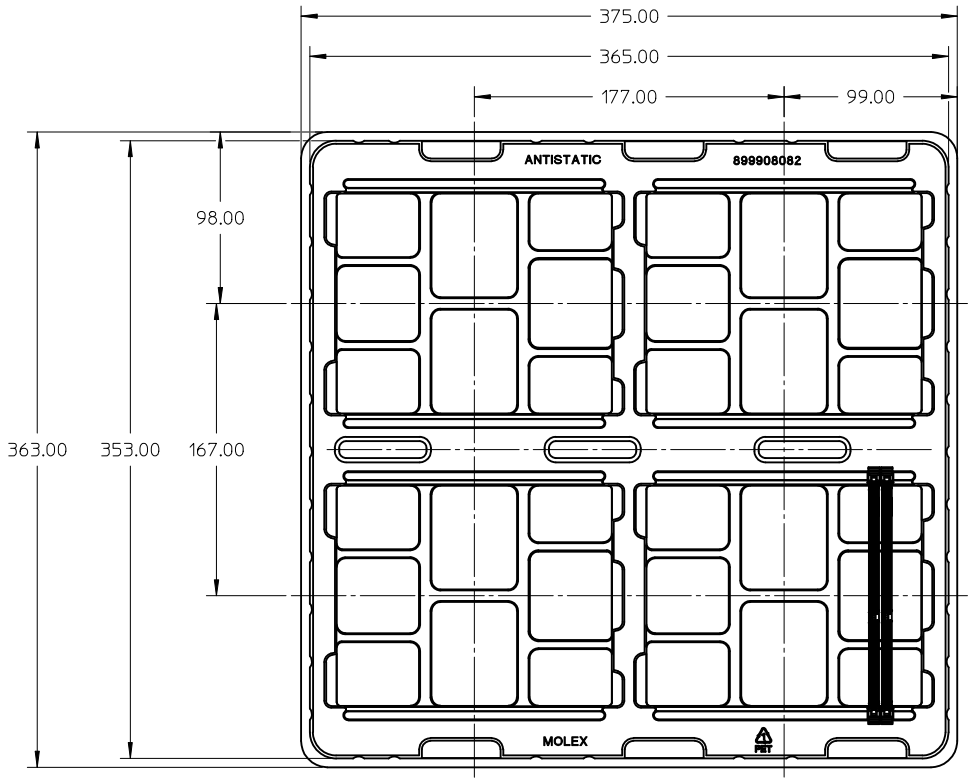
TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H

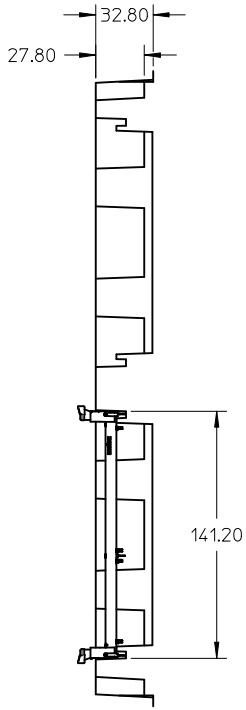
MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78079-001
SHEET NO.: 4 OF 8

SIZE A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION





NOTES:
1. QTY OF CAVITY: 20 X 4 = 80 PCS

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN:JAKEEMEW 2010/06/10
CH'KD:CCTEH 2010/06/13
APPR:SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
F_A=0
F_C=0
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10
MATERIAL NO.: SEE TABLE

TITLE: DDR3 DIMM, 1.00MM PITCH
240 CKTS, VERTICAL T/H

MOLEX INCORPORATED

DOCUMENT NO.: SD-78079-001
SHEET NO.: 5 OF 8

SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION
78079-0001	CENTRE (1.5V)	BLACK	BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0003				3.00	2.18		
78079-0002				3.18	2.36		
78079-0011				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0013				3.00	2.18		
78079-0012				3.18	2.36		
78079-0021				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0023				3.00	2.18		
78079-0022				3.18	2.36		
78079-0051			NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0053				3.00	2.18		
78079-0052				3.18	2.36		
78079-0061				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0063				3.00	2.18		
78079-0062				3.18	2.36		
78079-0071				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0073				3.00	2.18		
78079-0072				3.18	2.36		

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
F_A=0
F_C=0
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10

TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78079-001
SHEET NO.: 6 OF 8

SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION
78079-0201	CENTRE (1.5V)	BLUE	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0203				3.00	2.18		
78079-0202				3.18	2.36		
78079-0211				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0213				3.00	2.18		
78079-0212				3.18	2.36		
78079-0221				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0223				3.00	2.18		
78079-0222				3.18	2.36		
78079-0351		GREEN		2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0353				3.00	2.18		
78079-0352				3.18	2.36		
78079-0361				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0363				3.00	2.18		
78079-0362				3.18	2.36		
78079-0371				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0373				3.00	2.18		
78079-0372				3.18	2.36		

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
$\sqrt{F_A}$=0
$\sqrt{F_C}$=0
$\sqrt{F_P}$=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10

TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78079-001
SHEET NO.: 7 OF 8

SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION
78079-0101	CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0103				3.00	2.18		
78079-0102				3.18	2.36		
78079-0111				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0113				3.00	2.18		
78079-0112				3.18	2.36		
78079-0121				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0123				3.00	2.18		
78079-0122				3.18	2.36		

FORKLOCK UPDATED
EC NO: S2010-0888 2010/04/29
DRWN: JAKEEMEW 2010/06/10
CH'KD: CCTEH 2010/06/13
APPR: SHLENI
DESCRIPTION
REV

A4

QUALITY SYMBOLS
F_A=0
F_C=0
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.2	± ---
1 PLACE	± ---	± ---

ANGULAR ± 1 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: YTYANG01 DATE: 2006/08/11
CHECKED BY: SHLENI DATE: 2006/09/07
APPROVED BY: SHLENI DATE: 2010/06/10

TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78079-001
SHEET NO.: 8 OF 8

SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION